

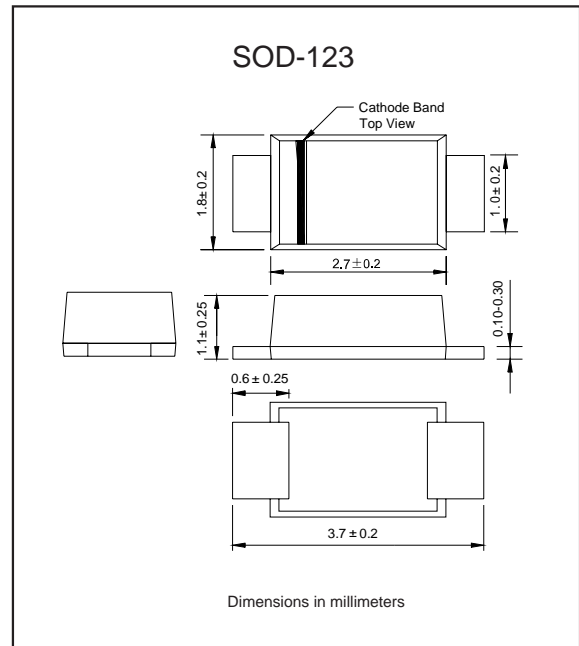
Features

- ▶ Glass passivated device
- ▶ Ideal for surface mouted applications
- ▶ Low reverse leakage
- ▶ Metallurgically bonded construction
- ▶ High temperature soldering guaranteed:
250°C/10 seconds,0.375"(9.5mm) lead length,
5 lbs. (2.3kg) tension
- ▶ Compliant to RoHS Directive 2011/65/EU
- ▶ Compliant to Halogen-free
- ▶ Suffix "-Q1" for AEC-Q101

Mechanical data

- ▶ **Case**: JEDEC SOD-123 molded plastic body over passivated chip
- ▶ **Terminals**: Plated axial leads, solderable per MIL-STD-750, Method 2026
- ▶ **Polarity**: Color band denotes cathode end
- ▶ **Mounting Position**: Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	I_O			2.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			50	A
Reverse current	$V_R = V_{RRM}$ $T_A = 25^\circ\text{C}$	I_R			5.0	μA
	$V_R = V_{RRM}$ $T_A = 100^\circ\text{C}$				50	
Thermal resistance	Junction to ambient NOTE 1	$R_{\theta JA}$		30		$^\circ\text{C}/\text{W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		45		pF
Storage temperature		T_{STG}	-65		+150	$^\circ\text{C}$

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	t_{rr}^{*5} (ns)	Operating temperature T_{Jr} ($^\circ\text{C}$)
DFR2A-Q1	50	35	50	1.30	150	-55 to +150
DFR2B-Q1	100	70	100			
DFR2D-Q1	200	140	200			
DFR2G-Q1	400	280	400		250	
DFR2J-Q1	600	420	600			
DFR2K-Q1	800	560	800			
DFR2M-Q1	1000	700	1000	500		

- *1 Repetitive peak reverse voltage
- *2 RMS voltage
- *3 Continuous reverse voltage
- *4 Maximum forward voltage@ $I_F=2.0\text{A}$
- *5 Maximum Reverse recovery time, note 2

Note: 1.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas
2. Reverse recovery time test condition, $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$

Rating and characteristic curves (DFR2A-Q1 THRU DFR2M-Q1)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

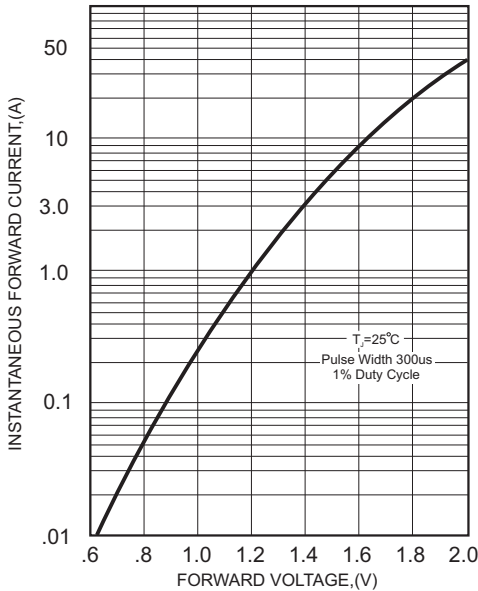


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

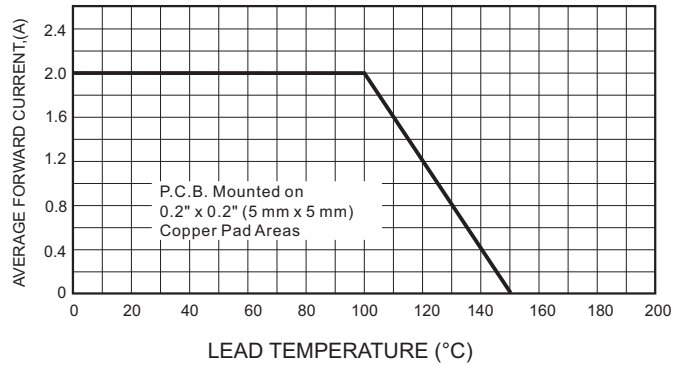


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

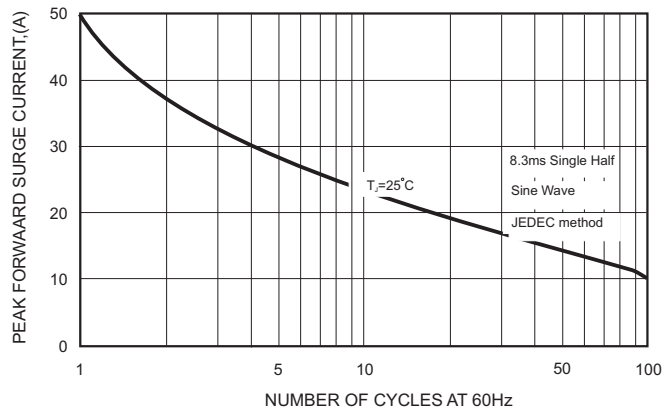
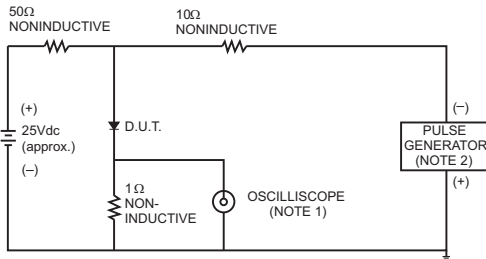


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm.22pF.
2. Rise Time= 10ns max., Source Impedance= 50 ohms.

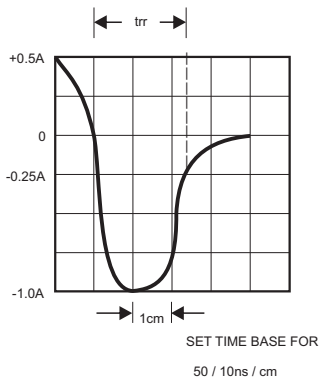
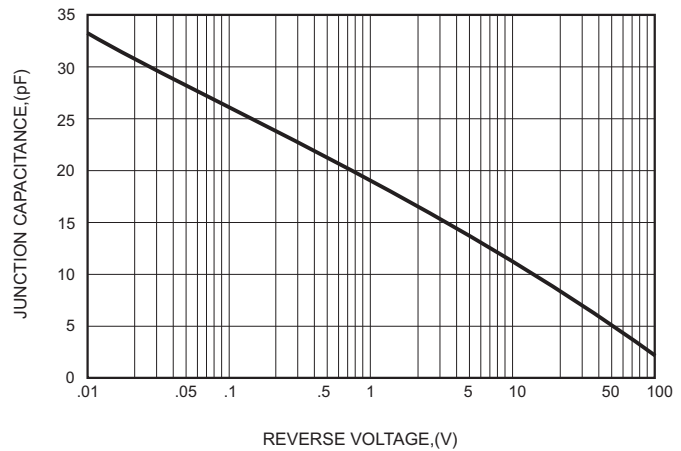




FIG.5-TYPICAL JUNCTION CAPACITANCE



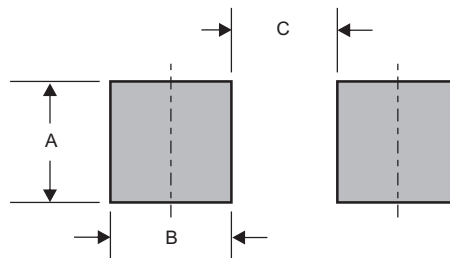
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
DFR2A-Q1	F 21
DFR2B-Q1	F 22
DFR2D-Q1	F 23
DFR2G-Q1	F 24
DFR2J-Q1	F 25
DFR2K-Q1	F 26
DFR2M-Q1	F 27

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-123	0.075 (1.90)	0.055 (1.40)	0.075 (1.90)